

Supply Chain Explorer

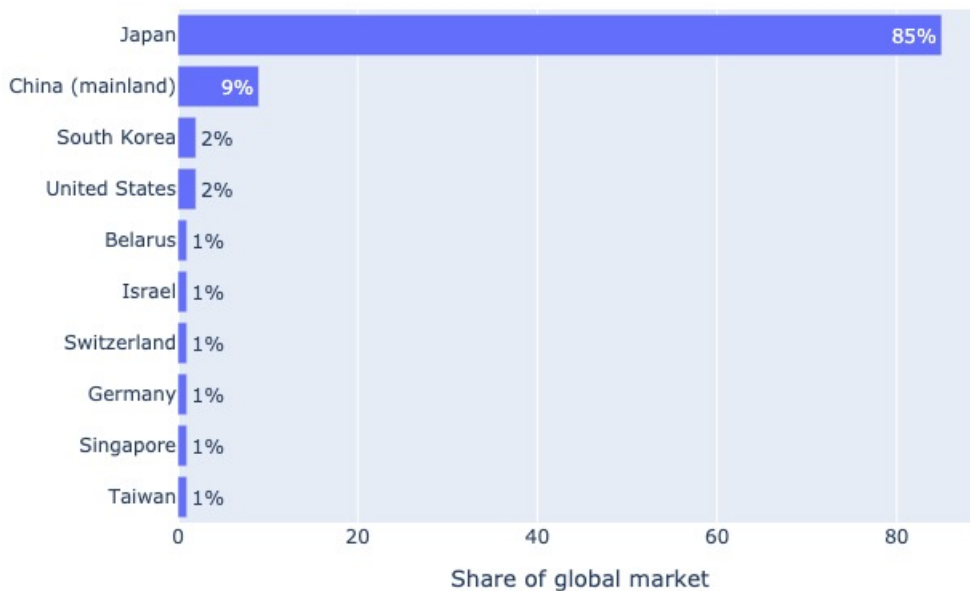
By the Emerging Technology Observatory

This is an export from the ETO Supply Chain Explorer, available at: <https://TBD.cset.tech> You can see the web version of this content at <https://TBD.cset.tech/?filter-choose=input-resource&input-resource=N71>.

Dicing tools

Dicing tools cut individual chips (dies) in the wafer into separated chips. This process also involves thinning the wafer. Dicing tools include blade saws, laser saws, dicing accessories and backside grinding equipment.

Country provision



Notable supplier companies

- ASM Pacific - China (mainland)
- Accretech - Japan
- Disco - Japan
- Longhill Industries - China (mainland)
- SYNOVA - China (mainland)